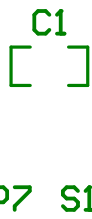
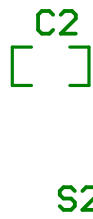


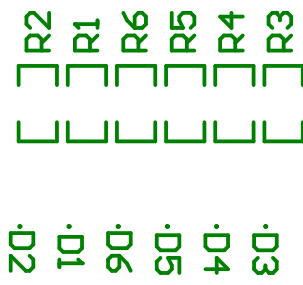
P7



S1



S2



R2

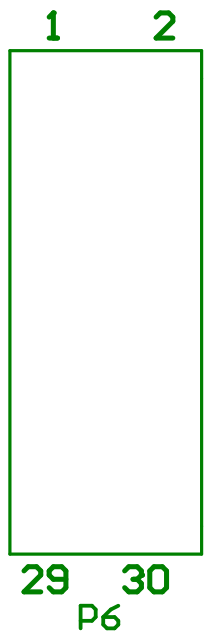
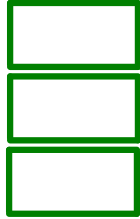
R1

R6

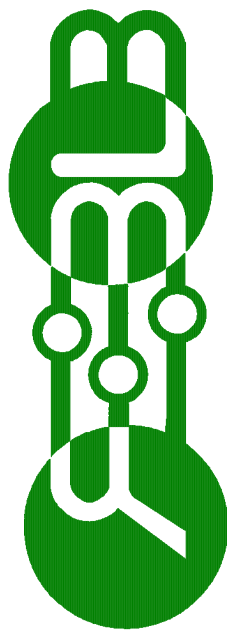
R5

R4

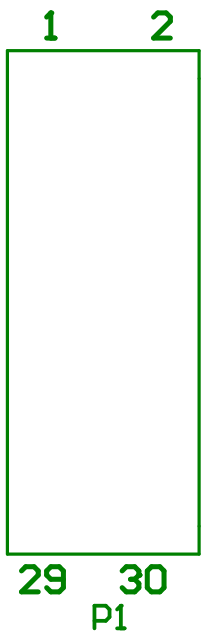
R3



P6



LoRaNode V2 DEBUG



P1



• GND  
PA0  
PB8  
PB9  
PB2  
GND  
PB7  
PB6  
PB5  
PA13  
GND  
PA14  
PA12  
PA11  
+3V3



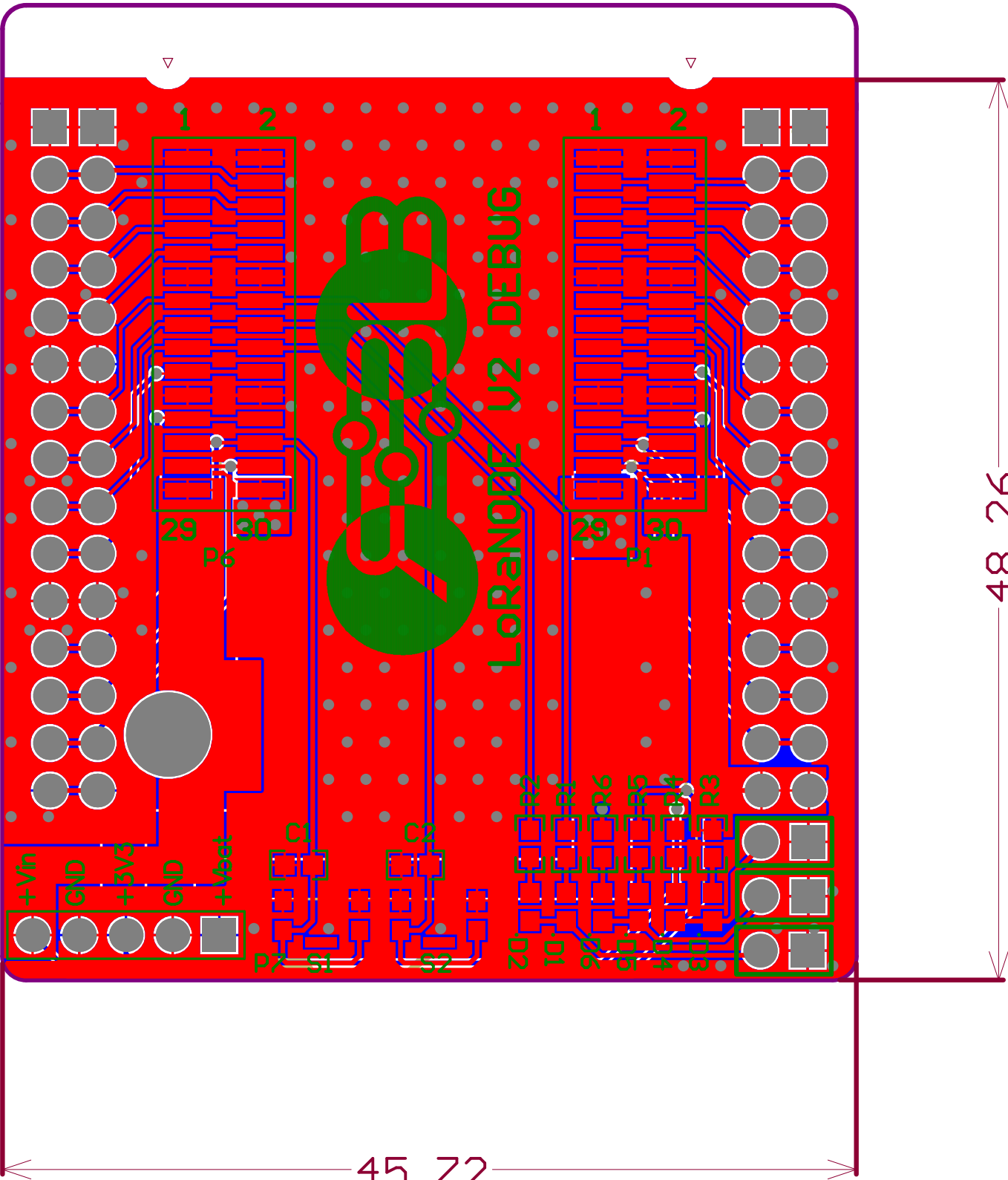
• GND  
PA2  
PA3  
PA4  
PA5  
GND  
PA8  
PA9  
PA10  
PB12  
GND  
PB13  
PB14  
PB15  
+3V3\_2

12  
16  
14

P2







Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				[Hatched Pattern]
	Top Solder	Solder Resist	0.50mil	3.8	
1	Top Layer		1.38mil		[Hatched Pattern]
	Dielectric	FR-4	59.06mil	4.5	
2	Bottom Layer		1.38mil		[Hatched Pattern]
	Bottom Solder	Solder Resist	0.50mil	3.8	
	Bottom Overlay				[Hatched Pattern]

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
○	192	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>
☆	71	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>
▽	3	90.55mil (2.300mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	<Mixed>
	266 Total							